ELECTRONIC PACKAGE WITH COMPRESSIBLE HEATSINK STRUCTURE

ABSTRACT

An electronic package (10) wherein an electronic device (e.g., chip) (18) on a circuitized substrate (12) of the package is thermally coupled to a heatsink (22) in a separable manner using a plurality of compressible, thermally conductive members (e.g., solder balls) (20). These members are compressed and permanently deformed as part of the thermal coupling.

Fig. 1

This Sheet Has Been Replaced



THIS SHEET HAS BEEN REPLACED